

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of: Noriyuki SAKUMA et al.
Conf.:
Appl. No.: NEW NON-PROVISIONAL
Group:
Filed: October 28, 2003
Examiner:
Title: WAFER POLISHING METHOD AND WAFER
POLISHING APPARATUS IN SEMICONDUCTOR
FABRICATION EQUIPMENT

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 28, 2003

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

Amendments to the Specification begin on page 2 of this paper.

Remarks begin on page 3 of this paper.

An **Appendix** is attached following the signature page of this paper.